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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LEI DENG	05/25/2017
YIN TANG	05/25/2017
TAO ZHAO	05/25/2017

RECEIVING PARTY DATA

Name:	SZ DJI TECHNOLOGY CO., LTD.
Street Address:	17/F WEST WING SKYWORTH SEMICONDUCTOR DESIGN BLDG., NO. 18 GAOXIN SOUTH 4TH AVENUE, NANSHAN DISTRICT
City:	SHENZHEN
State/Country:	CHINA
Postal Code:	518057

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16259661

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NAME OF SUBMITTER:	HOI CHEUNG	
SIGNATURE:	/Hoi Cheung/	
DATE SIGNED:	01/28/2019	

Total Attachments: 2

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PATENT REEL: 048159 FRAME: 0244

ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made

an invention entitled:
FASTENING ASSEMBLY, HOLDING MECHANISM, BRACKET AND REMOTE CONTROLLER USING THE HOLDING MECHANISM
for which I/We executed an application for United States Letters Patent concurrently herewith, as a national application in the United States of PCT Application No. <u>PCT/CN2014/092544</u> , or filed an application for United States Letters Patent on(Application No); and
WHEREAS, SZ DJI TECHNOLOGY CO., LTD., a limited company of P.R.China, whose post office address is 6F, HKUST SZ IER Bldg. No.9 Yuexing 1st Rd. Hi-Tech Park (South). Nanshan District Shenzhen. Guangdong, 518057, P.R. China (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transferr, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, titte, and interest in and to this invention, provisional Application No.
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful caths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the
Declaration and Power of Attorney in this application, to insert here in parentheses (Application No.
, filed) the filing date and application number of said application when known

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IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1: Name: Lei DENG Address. 6F, HKUST SZ IER Bldg. No.9 Yuexing 1st Rd. Hi-Tech Park (South), Nanshan District Shenzhen, Guangdong 518057 P.R. China Signature: Date: inventor 2: Name: Yin TANG 6F, HKUST SZ IER Bldg, No.9 Yuexing 1st Rd. Hi-Address: Tech Park (South), Nanshan District Shenzhen, Guangdong 518057 P.R. China Signature: Date: Inventor 3: Name: Tao ZHAO 6F, HKUST SZ IER Bidg. No 9 Yuexing 1st Rd. Hi-Address: Tech Park (South), Nanshan District Shenzhen, Guangdong 518057 P.R. China Signature: Date:

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